

Application No.: 10/700,785

Docket No.: JCLA11670-R

**REMARKS**

Applicant has carefully considered the Office Action dated December 12, 2007, and the amendments above together with the remarks that follow are presented in a bona fide effort to address all issues raised in the Action and thereby place this case in condition for allowance. Favorable reconsideration and allowance of the application and presently pending claims 1-5 and 7-18, as amended, are respectfully requested.

**Present Status of the Application**

The outstanding Office Action has rejected claims 1-5 and 7-18 under 35 U.S.C. 103(a) as being unpatentable over FIGs. 1 and 2 of Applicant Admitted Prior Art (hereinafter, "AAPA").

In response thereto, Applicant amends claims 1, 7, 8, 14, 16, and 18 and paragraph [0026] of the specification. Support for the aforesaid revised claims is able to be found throughout the specification, and no new matter has been introduced by virtue of the above amendments.

After carefully considering the remarks set forth in this Office Action and AAPA, Applicant hereby otherwise traverses the above-mentioned rejections, and it is believed that the presently pending claims 1-5 and 7-18 are in condition for allowance. Reconsideration and withdrawal of the Examiner's rejection are earnestly solicited.

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**Discussions of Amended Specification**

Applicant amends the paragraph [0026]. Upon entry of the amendments, it is disclosed that the sound-receiving module 340 has a cavity 328. The signal-transforming module 306 and the sound-receiving module 304 are disposed on the substrate 308, and the signal-transforming module 306 is accommodated in the cavity 328. The image-receiving module 302 is disposed on the sound-receiving module 304.

These amendments are made to explain the structure of the integrated audio/video sensor of FIG. 3. These amendments are supported by FIG. 3, and it is believed that no new matter is introduced.

**Discussions of Rejections under 35 U.S.C. 103(a)**

*Claims 1-5, 7 and 15-16 are rejected under 35 U.S.C. 103(a) as being unpatentable over FIGs. 1 and 2 of AAPA.* However, Applicant respectfully disagrees.

Responsive hereto, Applicant first submits that claim 1 has been revised to more clearly define the structure of the integrated audio/video sensor to overcome the rejections of 35 U.S.C 103(a). Now claim 1 is recited as follows:

"An integrated audio/video sensor, comprising:

a substrate;

an image-receiving module for sensing an image;

*a sound-receiving module with a cavity, for sensing a sound, disposed on the substrate, wherein the image-receiving module is disposed on the sound-receiving module and comprises an outer cavity casing with a membrane thereon, a fixed inner cavity casing, and an electrical*

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*insulator between the outer cavity casing and the fixed inner cavity casing; and*

*a signal-transforming module, disposed on the substrate and accommodated in the cavity, for transforming the received image and the received sound into an audio/video signal which comprises a video signal component and an audio signal component;*

wherein the signal-transforming module comprises an image-sensing chip for detecting the image and outputting the audio/video signal, an audio amplifier chip for detecting the sound, amplifying the sound detected and outputting the audio/video signal, and an audio/video processing chip for carrying out a post-processing of the audio/video signal.” *(Emphasis Added)*

In the Office Action, the Examiner has made an assertion that combining FIGs. 1 and 2 of AAPA is a matter of obvious engineering choice. Applicant does not agree with Examiner based on the following reasons.

FIGs. 1 and 2 of AAPA do not teach or disclose the structure of integrated audio/video sensor of claim 1 of the present invention. In claim 1, *the image-receiving module is disposed on the sound-receiving module and comprises an outer cavity casing with a membrane thereon, a fixed inner cavity casing, and an electrical insulator between the outer cavity casing and the fixed inner cavity casing.* Furthermore in claim 1, *the signal-transforming module is disposed on the substrate and accommodated in the cavity.* These features of claim 1 are the structure features of the integrated audio/video sensor, and FIGs. 1 and 2 of AAPA do not teach or disclose these structure features.

Since FIGs. 1 and 2 of AAPA do not disclose or teach the structure features of claim 1 at issue, claim 1 should be patentable over FIGs. 1 and 2 of AAPA.

Claims 2-5, 7 and 15-16 directly or indirectly depend on claim 1. Since the independent

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claim 1 should be patentable over FIGs. 1 and 2 of AAPA, claims 2-5, 7 and 15-16 should be also patentable over FIGs. 1 and 2 of AAPA.

*Claims 8, 9-14 and 17-18 are rejected under 35 U.S.C. 103(a) as being unpatentable over FIGs. 1 and 2 of AAPA. However, Applicant respectfully disagrees.*

Responsive hereto, Applicant first submits that claim 8 has been revised to more clearly define the structure of the integrated audio/video signal processing system to overcome the rejections of 35 U.S.C 103(a). Now claim 8 is recited as follows:

*"An integrated audio/video signal processing system, comprising:*

*an integrated audio/video sensor, comprising:*

*a substrate;*

*a sound-receiving module with a cavity, for sensing a sound, disposed on the substrate, wherein the image-receiving module is disposed on the sound-receiving module and comprises an outer cavity casing with a membrane thereon, a fixed inner cavity casing, and an electrical insulator between the outer cavity casing and the fixed inner cavity casing; and*

*a signal-transforming module, disposed on the substrate and accommodated in the cavity, for transforming the received image and the received sound into an audio/video signal, wherein the signal-transforming module comprises an image-sensing chip for detecting the image and outputting the audio/video signal, an audio amplifier chip for detecting the sound, amplifying the sound detected and outputting the audio/video signal, and an audio/video processing chip for carrying out a post-processing of the audio/video signal; and*

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an audio/video system for post-processing the audio/video signal." (*Emphasis Added*)

FIGs. 1 and 2 of AAPA do not teach or disclose the structure of integrated audio/video sensor of claim 8. The reasons for patentability of claim 8 are same as those of claim 1, and thus claim 8 should be patentable over FIGs. 1 and 2 of AAPA.

Claims 9-14 and 17-18 directly or indirectly depend on claim 8. Since the independent claim 8 should be patentable, claims 9-14 and 17-18 should be also patentable.

For at least the foregoing reasons, withdrawal of these rejections of claims 1-5 and 7-18 under 35 U.S.C. 103(a) is respectfully requested.

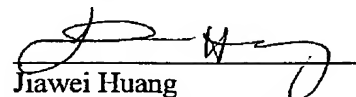
### CONCLUSION

If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application or resolve any outstanding issues, the Examiner is cordially invited to telephone the undersigned counsel to arrange for such a conference.

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